



Material Content Data Sheet



Sales Product Name		IPD50P04P4-13		Issued		31. July 2018		
MA#		MA000871866						
Package		PG-TO252-3-313		Weight*		317.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.525	0.48	0.48	4801	4801
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		464	
	non noble metal	copper	7440-50-8	147.096	46.31	46.37	463104	463707
	non noble metal	aluminium	7429-90-5	2.160	0.68	0.68	6800	6800
wire	non noble metal	aluminium	7429-90-5	2.160	0.68	0.68	6800	6800
encapsulation	organic material	carbon black	1333-86-4	1.407	0.44		4429	
	plastics	epoxy resin	-	24.620	7.75		77512	
	inorganic material	silicondioxide	60676-86-0	114.660	36.10	44.29	360986	442927
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11775	11775
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4472	4483
solder	non noble metal	tin	7440-31-5	0.032	0.01		101	
	noble metal	silver	7440-22-4	0.040	0.01		126	
	non noble metal	lead	7439-92-1	1.532	0.48	0.50	4825	5052
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.04	6.05	60377	60455
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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